Docket No.: SHIGA7.043APC Customer No. 20995

INFORMATION DISCLOSURE STATEMENT

Applicant : Hayashi et al.

App. No : 10/565,696

Filed: January 24, 2006

For : RESIN FOR RESIST, POSITIVE RESIST

COMPOSITION, AND METHOD OF

FORMING RESIST PATTERN

Examiner : Huhn, Richard A.

Art Unit : 1796

Conf No. : 5533

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified application is a PTO/SB/08 Equivalent listing 5 (five) references, of which 4 (four) are enclosed/submitted.

This Information Disclosure Statement is being filed before the mailing date of a final action and before the mailing date of a Notice of Allowance.

CERTIFICATION UNDER 37 C.F.R. § 1.97(e)(1)

I hereby certify that each item of information contained in this Statement was first cited in any communication from a foreign Patent Office in a counterpart foreign application not more than 30 days prior to the filing of this Information Disclosure Statement.

Thus, no fee is required as set forth in 37 C.F.R. § 1.97(c), however, the Commissioner is hereby authorized to charge any additional fees which may be required or to credit any overpayment to Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: April 7, 2010 By: /Neil S. Bartfeld/

Neil S. Bartfeld, Ph.D. Registration No. 39,901

Agent of Record Customer No. 20995 (619) 235-8550 Application No.: Filing Date: 10/565,696

January 24, 2006

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